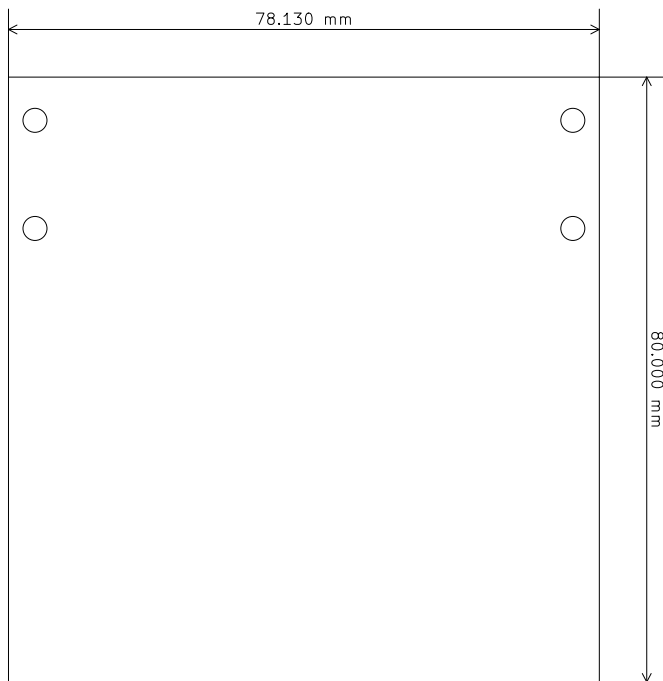




STACKUP

Layer	Thick.	SE Trace	Diff Trace
TOP	0.043	0.185 (50 Ohm)	0.165-0.14-0.165 (90 Ohm)
CORE	0.100		
L2.GND	0.018		
PREPREG 2116	0.105		
L3.SIG	0.018	0.14 (50 Ohm)	0.135-0.16-0.135 (90 Ohm)
CORE	0.930		
L4.SIG	0.018	0.14 (50 Ohm)	0.135-0.16-0.135 (90 Ohm)
PREPREG 2116	0.105		
L5.GND	0.018		
CORE	0.100		
BOTTOM	0.043	0.185 (50 Ohm)	0.165-0.14-0.165 (90 Ohm)
Board Thickness	1.498		

Default VIA diameters: 0.3mm drill, 0.6mm pad
 Small VIA diameters: 0.2mm - 0.4mm or 0.25mm - 0.5mm
 Default clearance: 0.125mm
 Around D2 clearance: 0.07mm

